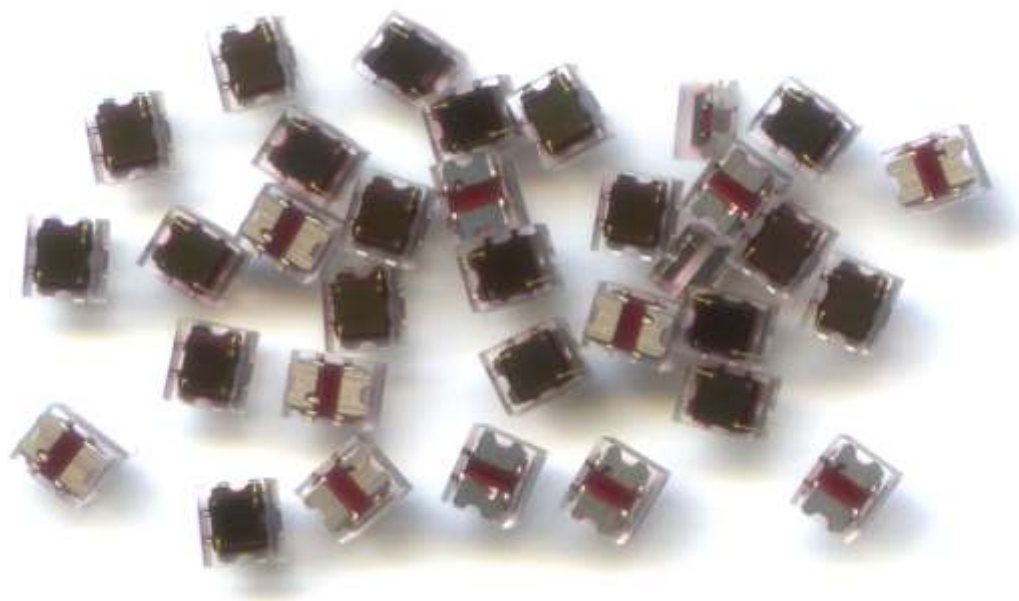


TN1000 Series SiPM

Performance and reliability



HIGHLIGHT FEATURES

- Excellent timing resolution
- Low dark count rate
- High PDE up to 35%
- Single photon sensitivity
- Excellent magnetic immunity
- Compact quad flat package

APPLICATIONS

- Gamma camera
- Spectral analyzer
- Light detection and range
- Fluorescence analysis
- Security inspection
- Low light imaging

Geometry Parameter

Product	Active Area	Pixel Pitch	No. of Pixels	Fill Factor	Package Dimension
JSP-TN1037-SMT	1mm×1mm	37 μm	576	60.2%	1.4mm×1.7mm×0.68mm
JSP-TN1050-SMT		50 μm	324	70.6%	

Performance Parameter

Parameter	Value		Condition	Unit
	JSP-TN1037-SMT	JSP-TN1050-SMT		
Spectral Response Range	250-950		--	nm
Peak Sensitivity Wavelength	420		--	nm
Breakdown Voltage	25±0.2		@ 25°C	V
Overvoltage ¹	1 - 5		--	V
PDE @420nm ²	32%	35%	V _{ov} =2V	--
Gain	2.1×10 ⁶	3.8×10 ⁶	V _{ov} =2V	--
Rise Time	880	900	V _{ov} =2V	ps
Recovery Time τ ³	20	34	V _{ov} =2V	ns
Dark Count Rate ⁴	Typ.	110	V _{ov} =2V	kHz/mm ²
	Max.	203	V _{ov} =2V	
Dark Current	Typ.	47	V _{ov} =2V	nA
	Max.	86	V _{ov} =2V	
Temperature Dependency of V _{br}	35.3	34.4	--	mV/°C
Crosstalk Probability	2.5%	3.5%	V _{ov} =2V	--
Afterpulse Probability	1.8%	2.0%	V _{ov} =2V	--
Pixel Capacitance	98	165	V _{ov} =2V	fF

1 Overvoltage (V_{ov}) =Operating Voltage (V_{op})-Breakdown Voltage (V_{br})

2 Photon detection efficiency does not include crosstalk and afterpulse

3 RC charging time of the pixel

4 Threshold=0.5 p.e at 25°C

General Parameters

JSP-TN1xxx-SMT	
Storage Temperature Range	-20℃~+45℃
Operating Temperature Range	-45℃~+85℃
Reflow Solder Compatibility	YES
Peak Temperature and Condition	250℃, 5second Xtwice
Cover Material	Epoxy Resin
Cover Refractive Index	1.54@589nm
Moisture Sensitivity Level	MSL3 ¹

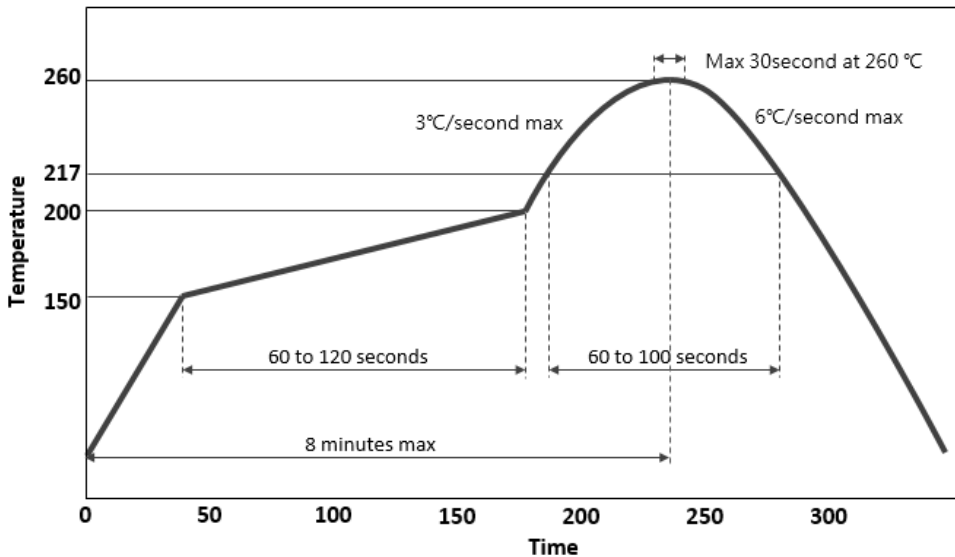
¹ Refer to JEDEC J-STD-020 standard, a MSL3 device is exposed at the condition of <30 °C, <60% RH, the device should be soldered within 168 hours. If the exposure time exceeds 168 hours, the device needs to be baked to remove the moisture inside the chips.

Soldering Condition

TN series SiPM are packed in tape & reel in MBB (Moisture Barrier Bag), Please follow the introductions below before reflow solder or other high temperature process:

1. Please don't open the MBB before the reflow solder process;
2. If the MBB is opened before reflow solder or other high temperature process, please follow the operating standard procedure of moisture sensitive device (JEDEC J-STD-033), the devices should be mounted within 168 hours. If the exposure time exceeds 168 hours, it needs to be baked to remove the moisture inside the chips before apply it to reflow solder.

To execute the reflow solder for surface mount type SiPM, the recommended temperature curve shown as below.

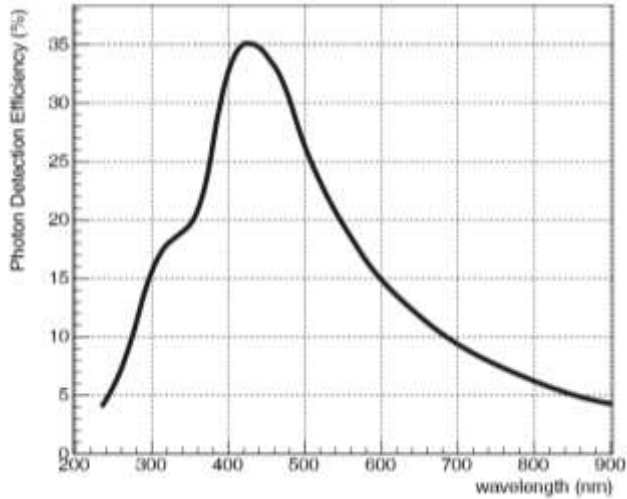


Recommended Temperature Curve

Performance Plots

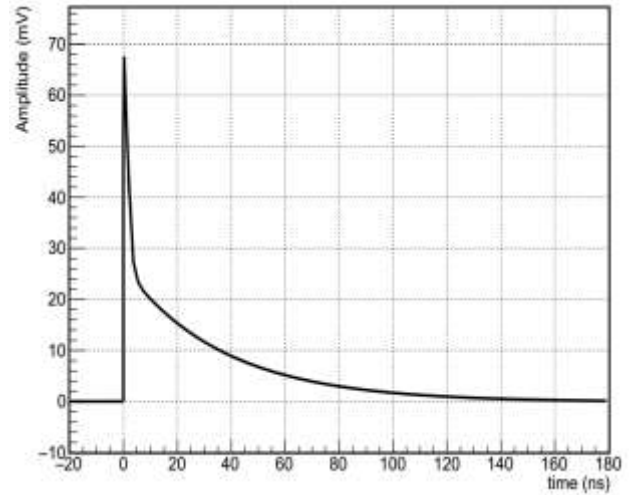
PDE versus Wavelength

JSP-TN1050-SMT



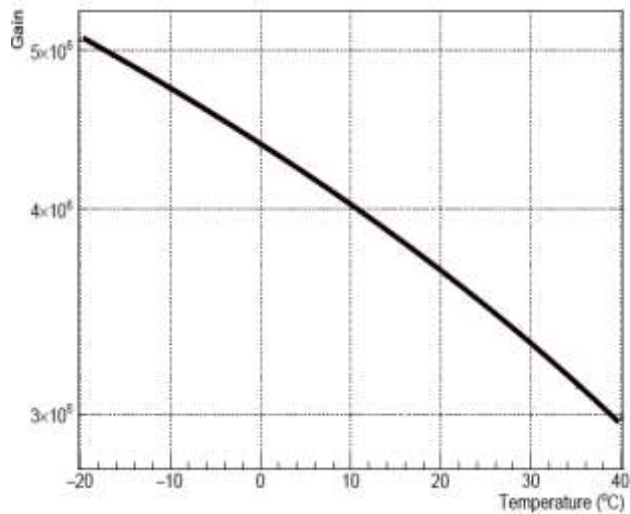
Typical Impulse Response

JSP-TN1050-SMT



Gain versus Temperature*

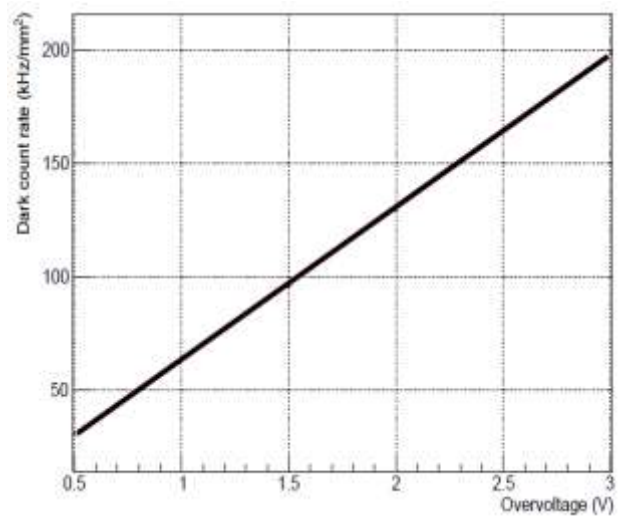
JSP-TN1050-SMT



*This data is tested at a fixed voltage of 26.9V (Vov=2V at room temperature, the breakdown voltage is typically 24.9V)

Dark Count Rate versus Overvoltage

JSP-TN1050-SMT

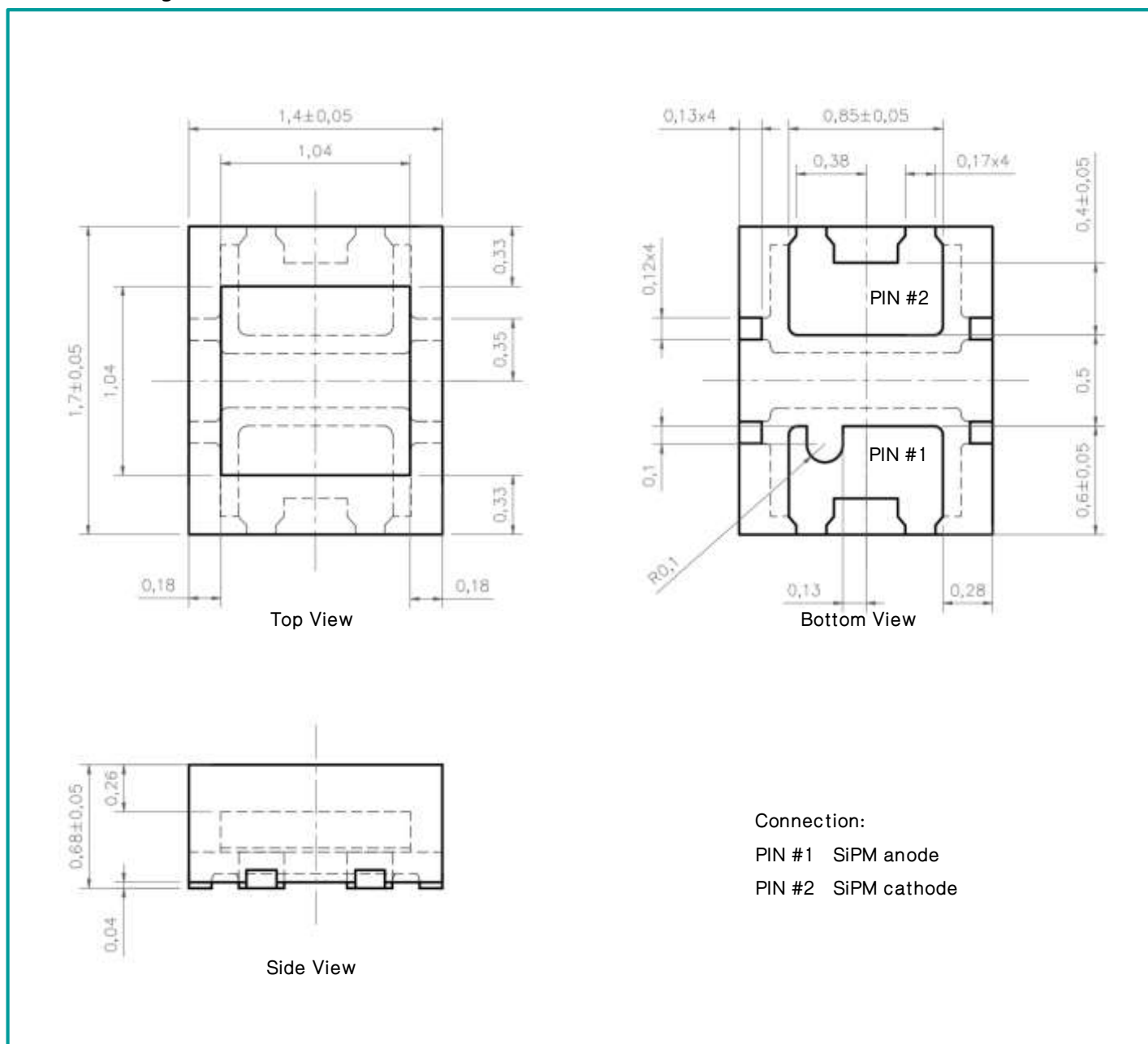


- 1 To use the product exceed the maximum rating condition may cause performance reduction or permanent damage
- 2 All the measurement are made at voltage of Vov=2V unless otherwise noted

Package Drawing

unit: mm

TN1-SMT Package Outline



The detailed drawing of TN1xxx-SMT is available to download here: [JSP-TN1xxx-SMT-CAD](#)

More information about the handling, storage, soldering and the basic of readout of TN series products is available to download.

[Handling, Storage and Soldering for SMT Products](#)

TN series SiPM has been certificated by Europe CE and RoHS certification, it is approved to be free of hazardous substances such as Pb, Hg, etc., which indicates TN series SiPM to be safe and environmentally friendly.



■ All specifications are subject to change without notice

Joinbon Technology Co., Ltd. (Hubei)



Building A03, East Lake Hi-Tech Innovation City, No.9 Phoenix Avenue, Phoenix Lake, Ezhou, Hubei, P.R.China.

Postcode: 436060

Tel: 027-5937 0337

Fax: 027-5937 0337

Email: info@joinbon.com

Site: www.joinbon.com